

<<电子组装技术专业英语>>

图书基本信息

书名：<<电子组装技术专业英语>>

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内容概要

《电子组装技术专业英语》按照生产企业电子组装工艺流程介绍了组装元器件、印制电路板、助焊剂、胶黏剂、焊料、清洗剂等材料的基本知识，介绍了电子组装生产线的组成、贴片机的基本结构和作用。

简要介绍了焊接技术、清洗技术、检测技术等电子组装各工艺环节的工艺方法，生产过程中的静电防护技术等内容。

《电子组装技术专业英语》适合作为应用型、技能型人才培养的大专院校(高职高专)应用电子类专业教材，也可作为电子组装专业技术培训用书，供从事电子组装工程技术人员参考。

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(2) Personal items such as plastic cups , thermos bottles , purses , sweaters , and other items of clothing should not be on work benches. (3) Care should be taken in handling of boards after mounting the components , and it may be noted that static damage may still result by improper handling of the stuffed boards.

(4) At the soldering area , the operator is required to wear wrist strap well ground-ed through a 1MW. It is better to have a common ground for the test equipment and for the static-free work stations. Even if we provide a separate grounding for static-free workstations , it is highly likely that the ground wires short each other at some point or the other along their length. Therefore , it is recommended , if in doubt to check the equipment grounding thoroughly instead of going-in for a separate grounding. (5) Insulative brushes are used for flux application and cleaning. This may result in generation of static leading to component damage. Use of cotton is recommended while cleaning or for flux application.

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